



Board Characteristics

- 0. This is a 12-Layer Board
- 1. Material FR4 with Tg>170C, E.g. FR406
- 2. Minimum trace width: 0.005" and clearance: 0.004" on Signal Layers
- 3. All dimensions are given in inches unless specified otherwise.
- 4. 1 oz copper for all power layers and for Signal_1 and 12 (Top and Bottom)
1/2 oz copper for Stripline trace layers (Signal_2,3,4,5,6,7).
- 5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
Apply Solder Mask over bare copper.
- 6. Board Thickness: 0.063
- 8. Silkscreen on Component and Solder Sides.
- 10. FHS tolerances: +/- 0.003 unless specified otherwise.
- 11. Interlayer spacing as specified
- 12. Zc=55 Ohm +/- 5 Ohm for 0.005" traces

BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.009	276	YES	---	
⊞	.01	1138	YES	---	
⊕	.035	366	YES	---	
⊞	.041	66	YES	---	
⊖	.042	20	YES	---	
⊞	.098425197	2	YES	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX .XXX DO NOT SCALE DRAWING			CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP		
TREATMENT			APPROVALS	DATE	TITLE		
FINISH			DRAWN M. Bogdan	3/5/2012	DRS4-Motherboard Specification Drawing		
SIMILAR TO			CHECKED M. Bogdan	3/5/2012	SIZE	FSCM NO.	DWG. NO. 2764
ACT. WT	CALC. WT		ISSUED				REV. A
					SCALE 1/2	SHEET	